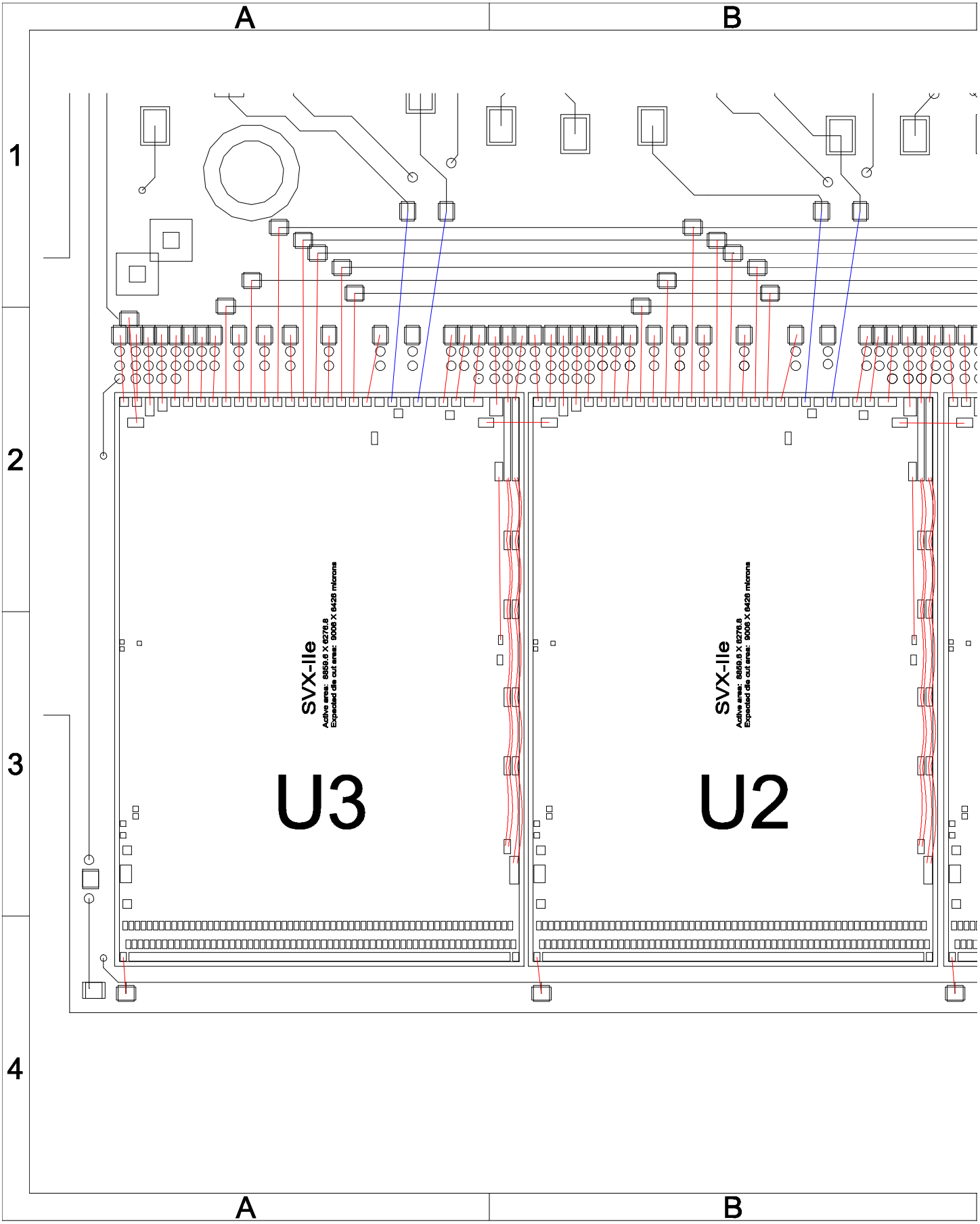
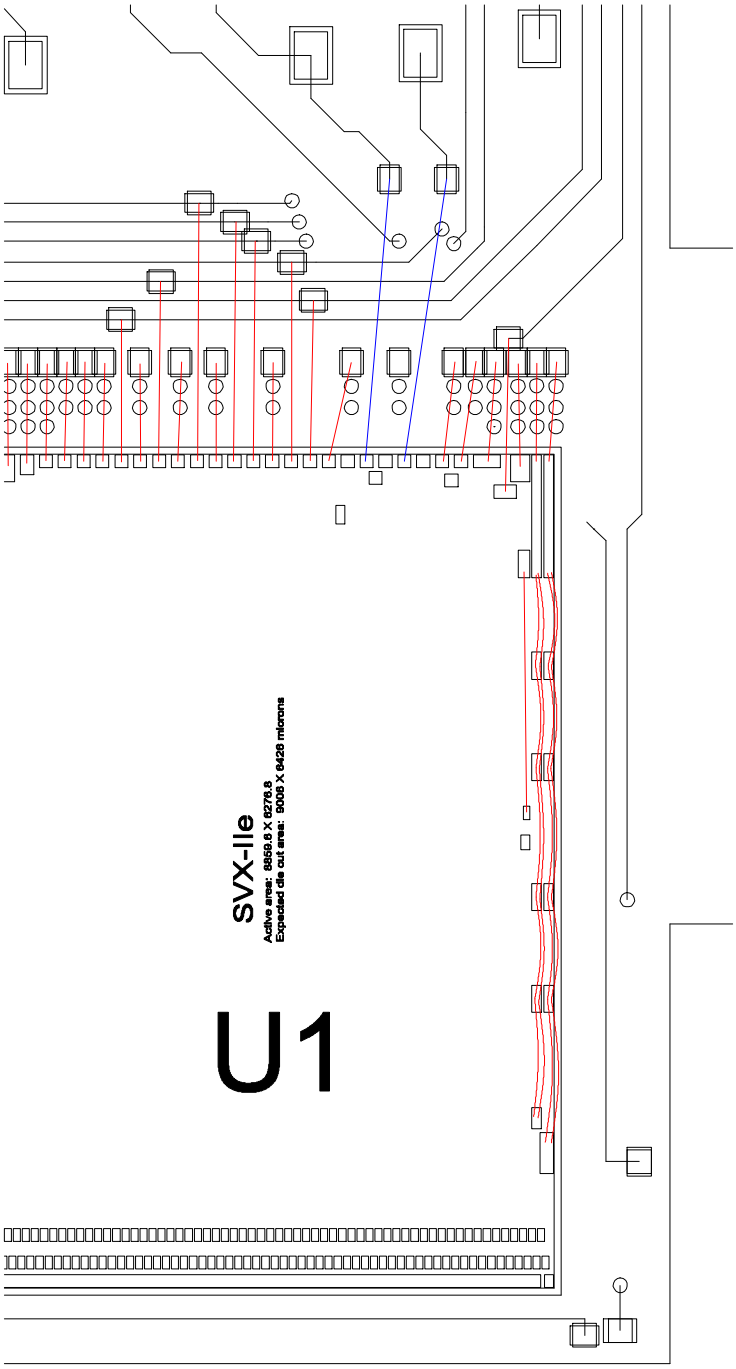

A
B
1
2
3
4
SVX-IIe
Active area: 8859.8 X 6276.8
Expected die cut area: 9008 X 6426 microns
U3
SVX-IIe
Active area: 8859.8 X 6276.8
Expected die cut area: 9008 X 6426 microns
U2
A
B

REV.	DESCRIPTION	DRAWN	DATE
		APPD.	DATE
B	ADDED PULL STRENGTH WIRE BONDS (IN BLUE)	MATULIK	01/11/00



NOTE:
APPLIES TO HDI CIRCUIT NUMBERS 3314 AND 3351 ONLY.

ITEM	PART NUMBER	DESCRIPTION OR SIZE	QTY
PARTS LIST			

UNLESS OTHERWISE SPEC.					
			ORIGINATOR	M. Matulik	02/24/98
			DRAWN BY	M. Matulik	02/24/98
			CHECKED BY		
			APPROVED BY		
			USED ON -		
			MATERIAL -		

FERMI NATIONAL ACCELERATOR LABORATORY
UNITED STATES DEPARTMENT OF ENERGY

THREE CHIP BARREL HDI LEFT HAND TAIL BONDING DIAGRAM

SCALE	FILMED	DRAWING NUMBER	Sheet 1 of 1	REV.
		3823.112-MB-330186		B